# 2SC1509

### Silicon NPN epitaxial planar type

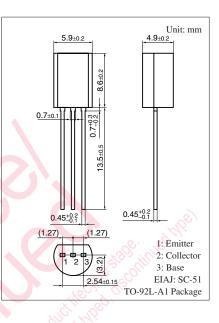
For low-frequency driver amplification Complementary to 2SA0777 (2SA777)

#### Features

- High collector-emitter voltage (Base open)  $V_{CEO}$
- Optimum for the driver stage of a low-frequency and 25 W to 30 W output amplifier

The solute maximum matings $T_a = 25$ C						
Symbol	Rating	Unit				
V <sub>CBO</sub>	80	V				
V <sub>CEO</sub>	80	v				
V <sub>EBO</sub>	5	V				
I <sub>C</sub>	0.5	А				
I <sub>CP</sub>	1	A				
P <sub>C</sub>	750	mW				
Tj	150	°C				
T <sub>stg</sub>	-55 to +150	°C				
	Symbol V <sub>CBO</sub> V <sub>CEO</sub> V <sub>EBO</sub> I <sub>C</sub> P <sub>C</sub> T <sub>j</sub>	Symbol Rating   V <sub>CBO</sub> 80   V <sub>CEO</sub> 80   V <sub>EBO</sub> 5   I <sub>C</sub> 0.5   I <sub>CP</sub> 1   P <sub>C</sub> 750   T <sub>j</sub> 150				





#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

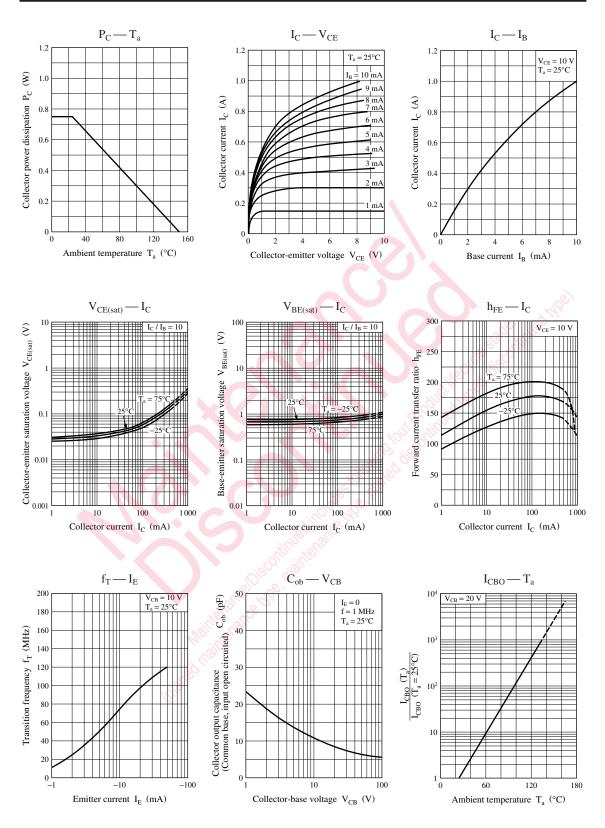
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_{\rm C} = 10 \ \mu A, \ I_{\rm E} = 0$	80			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{C} = 100 \ \mu A, I_{B} = 0$	80			V
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	$I_{\rm E} = 10 \ \mu A, \ I_{\rm C} = 0$	5			V
Collector-base cutoff current (Emitter open)	I <sub>CBO</sub>	$V_{CB} = 20 \text{ V}, I_E = 0$			0.1	μΑ
Forward current transfer ratio	h <sub>FE1</sub> *	$V_{CE} = 10 \text{ V}, \text{ I}_{C} = 150 \text{ mA}$	130		330	
	h <sub>FE2</sub>	$V_{CE} = 5 \text{ V}, I_C = 500 \text{ mA}$	50	100		_
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_{\rm C} = 300 \text{ mA}, I_{\rm B} = 30 \text{ mA}$		0.2	0.4	V
Base-emitter saturation voltage	V <sub>BE(sat)</sub>	$I_{\rm C} = 300 \text{ mA}, I_{\rm B} = 30 \text{ mA}$		0.85	1.2	V
Transition frequency	f <sub>T</sub>	$V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		120		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		11	20	pF
(Common base, input open circuited)						

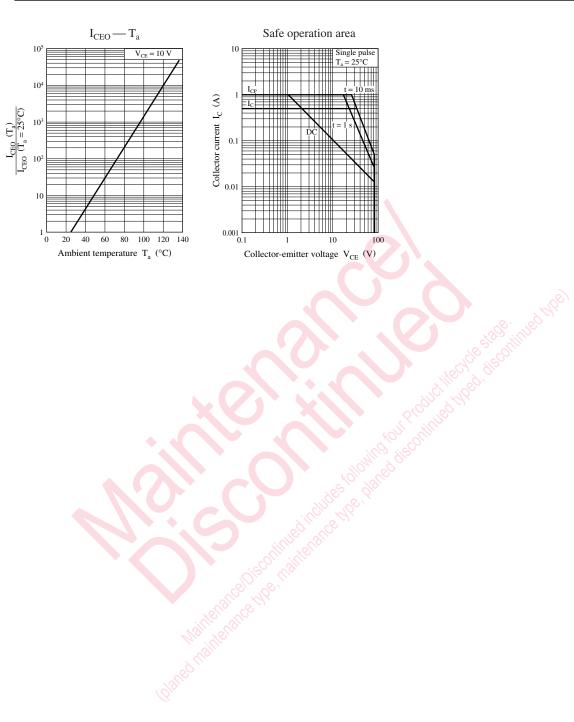
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors. 2. \*: Rank classification

Rank	R	S
h <sub>FE1</sub>	130 to 220	185 to 330

Note) The part number in the parenthesis shows conventional part number.

### **Panasonic**





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